



Material Content Data Sheet



Sales Product Name		IDB30E120		Issued		29. August 2013		
MA#		MA000665798						
Package		PG-TO263-3-2		Weight*		1462.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.037	0.28	0.28	2760	2760
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		583	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175	
	non noble metal	copper	7440-50-8	851.691	58.21	58.29	582197	582955
wire	non noble metal	aluminium	7429-90-5	3.046	0.21	0.21	2083	2083
encapsulation	organic material	carbon black	1333-86-4	8.847	0.60		6047	
	plastics	epoxy resin	-	97.314	6.65		66522	
	inorganic material	silicondioxide	60676-86-0	483.620	33.06	40.31	330593	403162
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6601	6601
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	noble metal	silver	7440-22-4	0.083	0.01		57	
	non noble metal	tin	7440-31-5	0.067	0.00		46	
	non noble metal	lead	7439-92-1	3.189	0.22	0.23	2180	2283
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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